

Material Set Change Description:

Package	Material	CARSEM	AMKOR
SOT23 5/6/8 Leads	Mold Compound	Hitachi CEL 8240 HF10LX	Sumitomo G700LS
	Die Attach Adhesive	Hysol QMI 519	Ablestik 84-1 LMISR4

Mold Surface Finish: Smooth Surface Finish (Carsem) - Matte Surface Finish (Amkor)

**Addition of Amkor Philippines as Alternate Assembly Site
for 5L, 6L, and 8L SOT23 Packages**

**Qualification Results Summary
for 5L, 6L, and 8L SOT23 at Amkor Philippines**

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Pass
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 77	Pass
Electrostatic Discharge <i>Field-Induced Charge Device Model</i>	JEDEC <i>JESD22-AC101</i>	3 / voltage	Pass ±1250V

*Preconditioned per JEDEC/IPC J-STD-020